



S/N 09/838,493

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Dinesh Chopra

Examiner: Khiem D. Nguyen

Serial No.: 09/838,493

Group Art Unit: 2823

Filed: April 19, 2001

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Title: COMBINED BARRIER LAYER AND SEED LAYER

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**Commissioner for Patents  
Washington, D.C. 202316/B  
FOLLOWES  
JAN 22 2003  
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TECHNOLOGY CENTER 2800

Applicant has reviewed the Office Action mailed on October 8, 2002. Please amend the above-identified patent application as follows.

**IN THE CLAIMS**

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claims 10, 15 and 42, and amendment of previously pending claims 1, 11-13, 16-32, 43-45, 47 and 54-57. The specific amendments to individual claims are detailed in the following marked up set of claims.

Please delete claims 10, 15, and 42

Please amended claims 1, 11-32, 43-45, 47 and 54-57 as follows:

1. (Once Amended) A method of metallizing a substrate, comprising:  
depositing a dual-purpose layer on the substrate;  
electrochemically reducing oxides on the surface of the dual-purpose layer using a first electrolyte where the first electrolyte is the cation of the anode in an electrochemical reaction cell; and  
electrochemically depositing a conductive interconnect layer on the surface of the dual-purpose layer using a second electrolyte.
  
11. (Once Amended) The method of claim 12 [10], wherein the anode is formed from titanium or titanized platinum.